

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

PESDXXVL1BA

Product specification

FEATURES

- I IEC61000-4-2 (ESD) ±30kV (Contact)
±30kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- 350 Watts Peak Pulse Power per (tp=8/20µs)
- Protects one I/O line (bidirectional)
- Low clamping voltage
- Working voltages:
3V,5V,8V,12V,15V,18V,20V,24V,36V
- Low leakage current


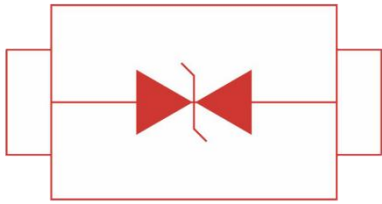
MACHANICAL DATA

- SOD-323 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- High temperature soldering guaranteed:
260°C/10s
- Reel size: 7 inch
- MSL 1

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports.
- Peripherals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
SOD-323	

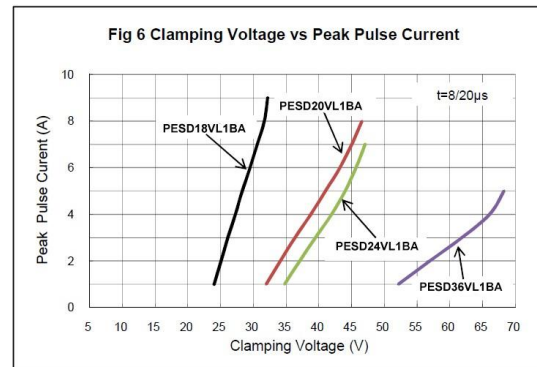
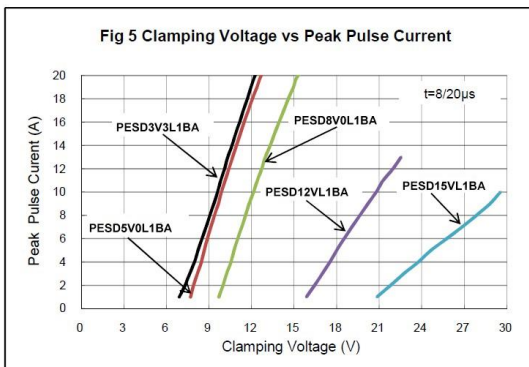
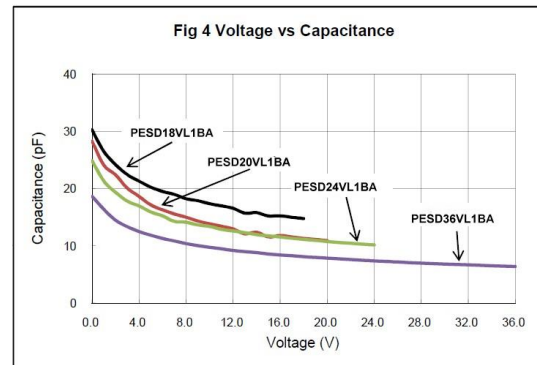
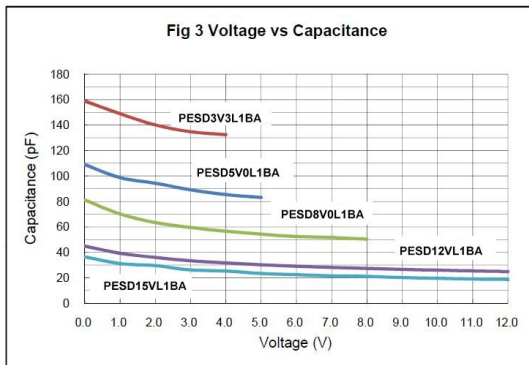
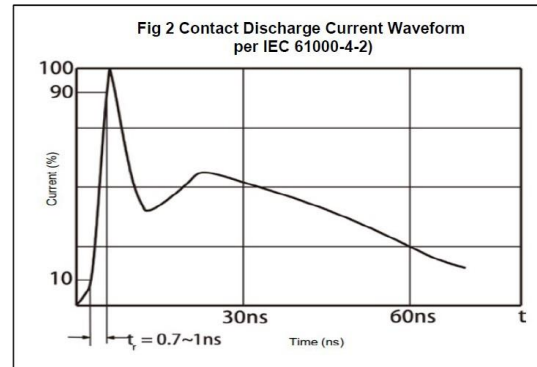
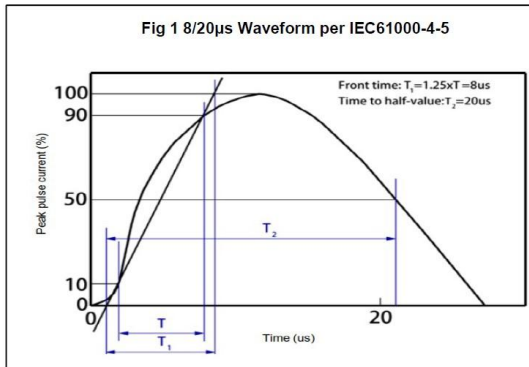
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
P _{PP}	Peak Pulse Power (8/20μs)	350	W
T _{OPT}	Operating Temperature	-55/+150	°C
T _{STG}	Storage Temperature	-55/+150	°C

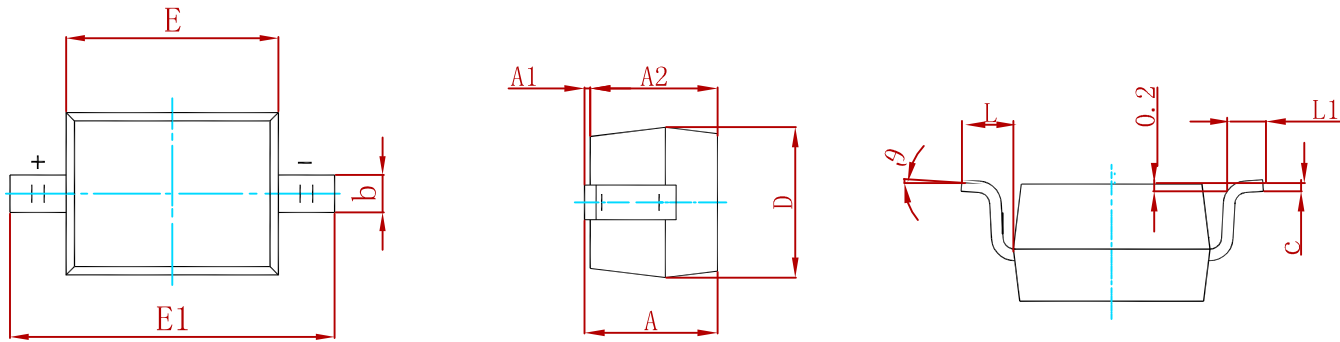
ELECTRICAL CHARACTERISTICS (Tamb=25°C)

PART NUMBER	DEVICE MARKING	V _{RWM} (V) (max.)	V _B (V) (min.)	I _r (mA)	V _{C@1A} (V) (max.)	V _C (V) (max.) (@A)		I _R (μA) (max.)	C _T (pF) (max.)
PESD3V3L1BA	2A	3.3	4.0	1	7.5	16.0	20	40	450
PESD5VOL1BA	2B	5.0	6.0	1	9.8	18.0	17	10	200
PESD8VOL1BA	2C	8.0	8.5	1	13.4	24.0	15	2	120
PESD12VL1BA	2D	12.0	13.3	1	19.0	32.0	11	1	75
PESD15VL1BA	2J	15.0	16.7	1	24.0	38.0	10	1	68
PESD18VL1BA	2K	18.0	20.0	1	29.0	45.0	9	1	57
PESD20VL1BA	2L	20.0	22.3	1	35.0	50.0	8	1	52
PESD24VL1BA	2H	24.0	26.7	1	43.0	52.0	7	1	50
PESD36VL1BA	2N	36.0	40.0	1	60.0	75.0	4.5	1	35

ELECTRICAL CHARACTERISTICS CURVE

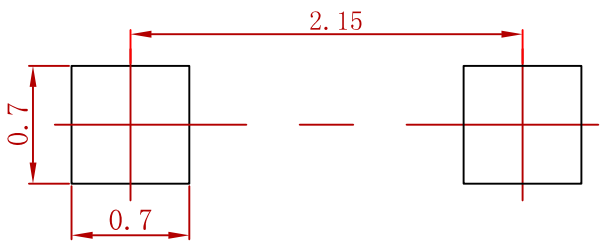


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PESDXXVL1BA	SOD-323	3000

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